

SID

Factory: Rot am See

Article:

525

ML6

Provided:

Kracht, Enrico

Customer:

Date:

10.08.2015



Processtechnology: B: undefiniert

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1	
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	150		2	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		3	
		70	L2		
C-RS-FR4-ML-0.30mm-070+070-TG150-HF	50200982	300		4	A01
		70	L3		
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	160		5	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		6	B00
		70	L4		
C-RS-FR4-ML-0.30mm-070+070-TG150-HF	50200982	300		7	A02
		70	L5		
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	150		8	
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		9	
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	10	

Thickness after Pressing

B00:

1440 µm

Tol+:

155 µm

Tol-:

155 µm

Dmax:

1595 µm

Dmin:

1285 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

1550 µm

Tol+:

155 µm

Tol-:

155 µm

Dmax:

1705 µm

Dmin:

1395 µm

Measuring point:

(05) über LM und galv.Cu; beidseitig

nominal:

1376 µm

Version 1.2.14.15

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